2SC4212

Silicon NPN triple diffusion planar type

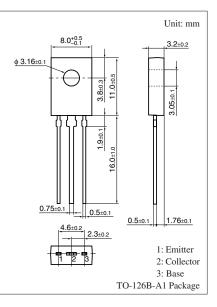
For color TV horizontal deflection driver

Features

- High collector-emitter voltage (Base open) V_{CEO}
- TO-126B package which requires no insulation plate for installation to the heat sink

Absolute Maximum Hatings $T_a = 25$ C							
Parameter	Symbol	Rating	Unit				
Collector-base voltage (Emitter open)	V _{CBO}	350	V				
Collector-emitter voltage (Base open)	V _{CEO}	300	V				
Emitter-base voltage (Collector open)	V _{EBO}	7.5	V				
Collector current	I _C	200	mA				
Peak collector current	I _{CP}	400	mA				
Collector power	P _C	1.2	W				
dissipation		5.0 *					
Junction temperature	Tj	150	°C				
Storage temperature	T _{stg}	-55 to +150	°C				

Absolute Maximum Ratings $T_a = 25^{\circ}C$



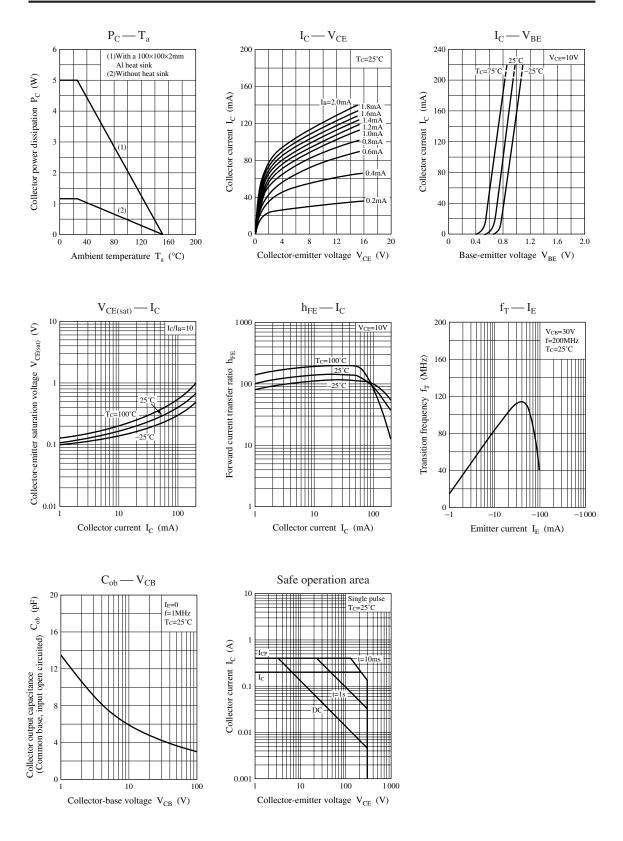
Note) *: With a $100 \times 100 \times 2$ mm Al heat sink

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 100 \ \mu A, \ I_{\rm E} = 0$	350			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 5 \text{ mA}, I_{\rm B} = 0$	300			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = 100 \ \mu A, \ I_C = 0$	7.5			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 200 \text{ V}, I_E = 0$			2	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 5 V, I_C = 0$			2	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 10 \text{ V}, \text{ I}_{C} = 10 \text{ mA}$	40		250	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 50 \text{ mA}, I_{\rm B} = 5 \text{ mA}$			1	V
Transition frequency	f _T	$V_{CB} = 30 \text{ V}, I_E = -10 \text{ mA}, f = 200 \text{ MHz}$	50	80		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 50 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			4.5	pF
(Common base, input open circuited)						

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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